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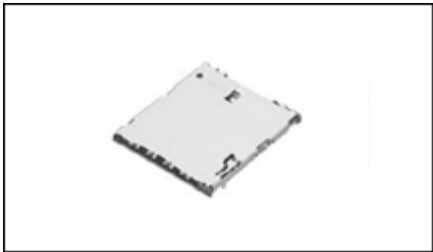
For microSIM Card (Push-push Type) SCGD Series

Detail

Part number	SCGD1B0201	
Applicable media	microSIM card	
Media ejection structure	Push-push type	
Mounting type	Surface mounting type	
Mounting style	Standard mount	
Card eject stroke	3mm	
Stand-off	0mm	
Minimum order unit (pcs.)	1,600	
Operating temperature range	-25 to +60	
Voltage proof	250V AC 1 minute	
Insulation resistance (Initial)	1,000MΩ min.	
Contact resistance (Initial)	Connector contacts	100mΩ max.
	Detection Switch	500mΩ max.
Insertion and removal cycle	5,000 cycles	
3D CAD (STEP)	Download	

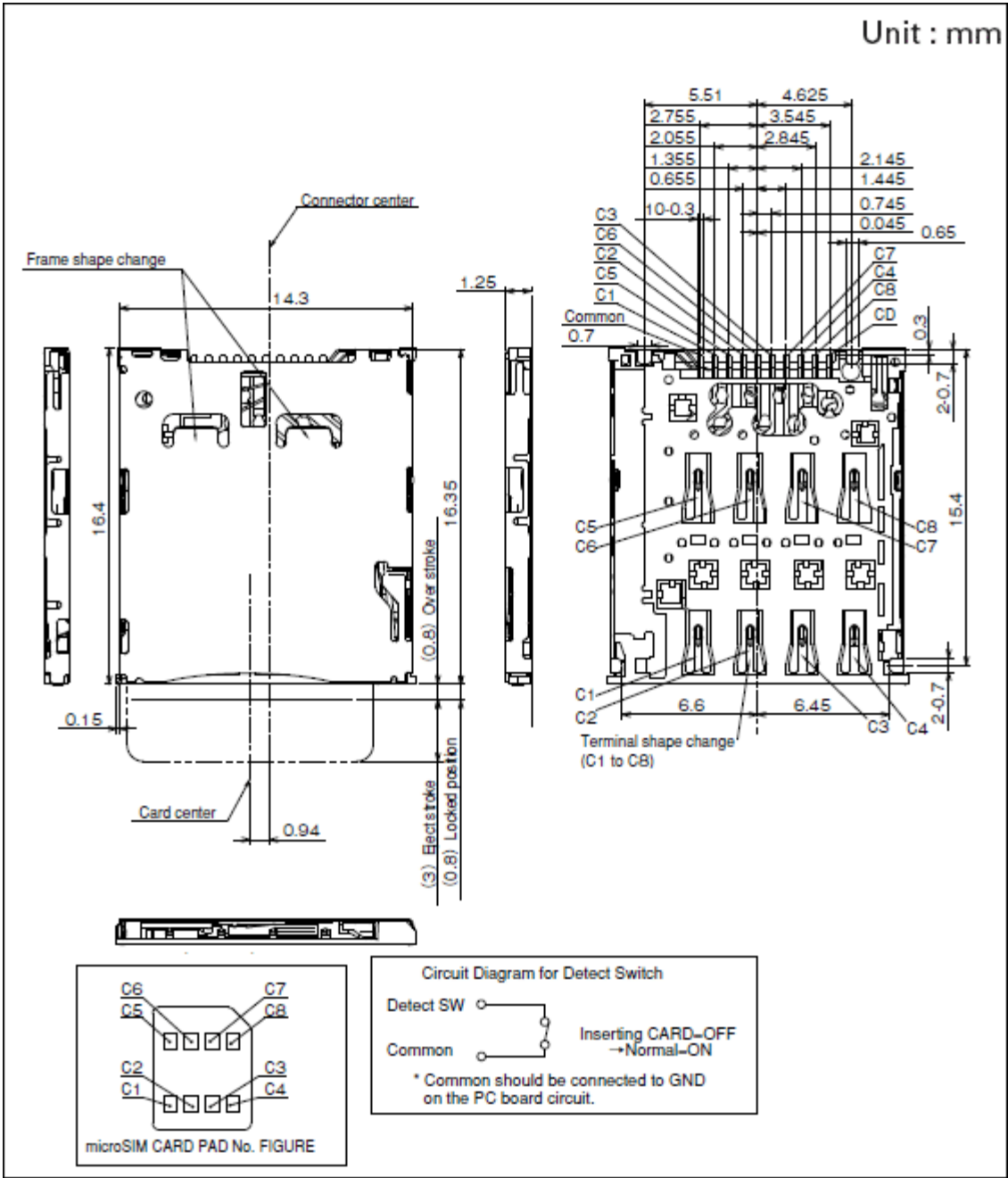
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Photo



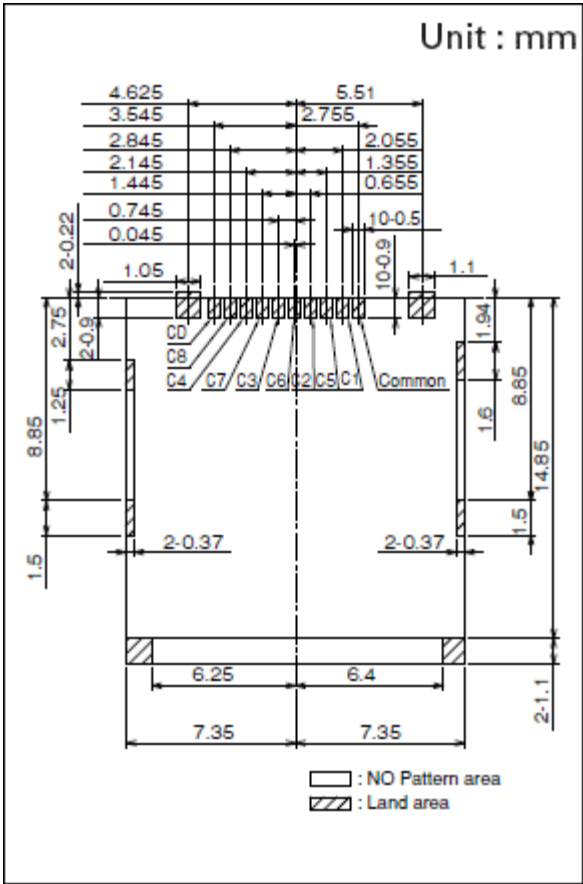
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●● Dimensions



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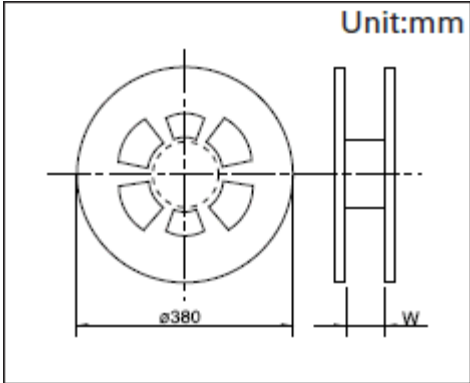
●● Mounting Dimensions



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● Packing Specifications

Taping

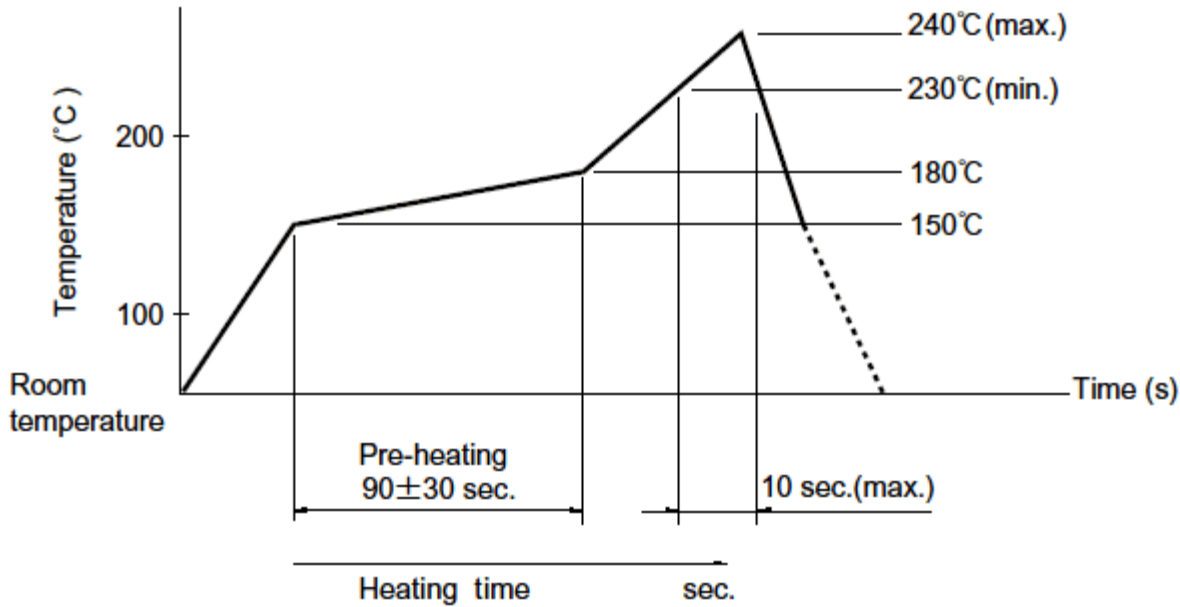


Number of packages (pcs.)	1 reel	1,600
	1 case / Japan	4,800
	1 case / export packing	9,600
Reel width W(mm)		57.5
Tape width (mm)		56
Export package measurements (mm)		403×403×303

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method
Double heating method with infrared heater.
- 2. Temperature measurement
Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion.
- 3. Temperature profile.



NOTE Notes are common to this series/models.

- 1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
- 2. Please place purchase orders per minimum order unit (integer).

? Inquiries about Products
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